

To all our customers

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## **Regarding the change of names mentioned in the document, such as Mitsubishi Electric and Mitsubishi XX, to Renesas Technology Corp.**

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The semiconductor operations of Hitachi and Mitsubishi Electric were transferred to Renesas Technology Corporation on April 1st 2003. These operations include microcomputer, logic, analog and discrete devices, and memory chips other than DRAMs (flash memory, SRAMs etc.) Accordingly, although Mitsubishi Electric, Mitsubishi Electric Corporation, Mitsubishi Semiconductors, and other Mitsubishi brand names are mentioned in the document, these names have in fact all been changed to Renesas Technology Corp. Thank you for your understanding. Except for our corporate trademark, logo and corporate statement, no changes whatsoever have been made to the contents of the document, and these changes do not constitute any alteration to the contents of the document itself.


Note : Mitsubishi Electric will continue the business operations of high frequency & optical devices and power devices.

Renesas Technology Corp.  
Customer Support Dept.  
April 1, 2003

MITSUBISHI IGBT  
**CY25AAJ-8F**

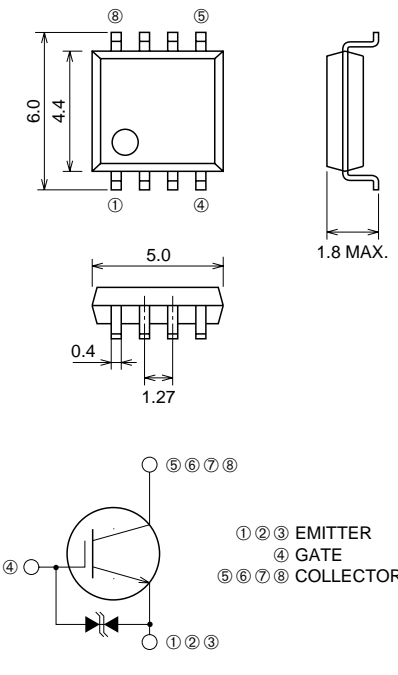
Nch IGBT for STROBE FLASHER

**CY25AAJ-8F**



- VCES ..... 400V
- ICM ..... 150A
- Drive voltage ..... 4V

**OUTLINE DRAWING** Dimensions in mm



**SOP-8**

**APPLICATION**

Strobe Flasher for camera

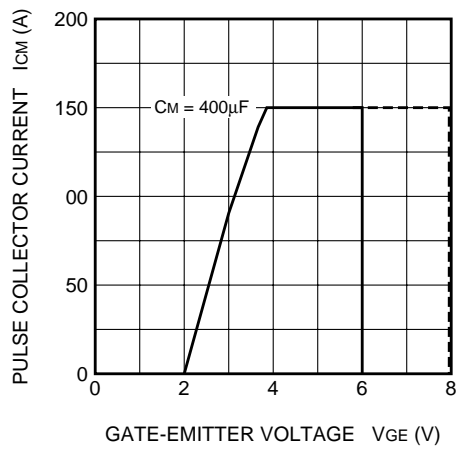
**MAXIMUM RATINGS** (Tc = 25°C)

Symbol	Parameter	Conditions	Ratings	Unit
V <sub>CE</sub> S	Collector-emitter voltage	V <sub>GE</sub> = 0V	400	V
V <sub>GE</sub> S	Gate-emitter voltage	V <sub>CE</sub> = 0V	±6	V
V <sub>GEM</sub>	Peak gate-emitter voltage	V <sub>CE</sub> = 0V, t <sub>w</sub> = 10s	±8	V
I <sub>CM</sub>	Collector current (Pulsed)	C <sub>M</sub> = 400μF see figure1	150	A
T <sub>j</sub>	Junction temperature		-40 ~ +150	°C
T <sub>stg</sub>	Storage temperature		-40 ~ +150	°C

**ELECTRICAL CHARACTERISTICS** ( $T_j = 25^\circ\text{C}$ )

Symbol	Parameter	Test conditions	Limits			Unit
			Min.	Typ.	Max.	
V (BR) CES	Collector-emitter breakdown voltage	$I_C = 1\text{mA}, V_{GE} = 0\text{V}$	450	—	—	V
V (BR) GES	Gate-emitter breakdown voltage	$I_G = \pm 100\mu\text{A}, V_{CE} = 0\text{V}$	$\pm 8$	—	—	V
ICES	Collector-emitter leakage current	$V_{CE} = 400\text{V}, V_{GE} = 0\text{V}$	—	—	10	$\mu\text{A}$
IGES	Gate-emitter leakage current	$V_{GE} = \pm 6\text{V}, V_{CE} = 0\text{V}$	—	—	$\pm 10$	$\mu\text{A}$
VGE (th)	Gate-emitter threshold voltage	$V_{CE} = 10\text{V}, I_C = 1\text{mA}$	—	—	1.5	V

**Figure1. MAXIMUM PULSE COLLECTOR CURRENT**



**APPLICATION EXAMPLE**

